OUTPUTS



Data sheet acquired from Harris Semiconductor SCHS100

# CMOS Decade Up-Down Counter/Latch/Display Driver

High-Voltage Type (20-V Rating)





#### Features:

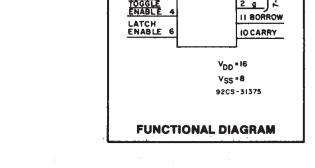
- Separate clock-up and clock-down lines-
- Capable of driving common cathode LEDs and other displays directly
- Allows cascading without any external circuitry
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V over full packagetemperature range; 100 nA at 18 V and 25° C

■ CD40110B is a dual\_clocked up/down counter with a special preconditioning circuit that allows the counter to be clocked, via positive going inputs, up or down regardless of the state or timing (within 100 ns typ.) of the other clock line.

The clock signal is fed into the control logic and Johnson counter after it is preconditioned. The outputs of the Johnson counter (which include anti-lock gating to avoid being locked at an illegal state) are fed into a latch. This data can be fed directly to the decoder through the latch or can be strobed to hold a particular count while the Johnson counter continues to be clocked. The decoder feeds a seven-segment bipolar output driver which can source up to 25 mA to drive LEDs and other displays such as low-voltage fluorescent and incandescent lamps.

A short durating negative-going pulse appears on the BORROW output when the count changes from 0 to 9 or the CARRY output when the count changes from 9 to 0. At the other times the BORROW and CARRY outputs are a logic 1.

The CARRY and BORROW outputs can be tied directly to the clock-up and clock-down lines respectively of another CD40110B for easy cascading of several counters.



CLK UP

CLK DN

RESET

CD40110B Types

- Noise margin (full package-temperature range) =
  - 1 V at V<sub>DD</sub> = 5 V
  - 2 V at V<sub>DD</sub> = 10 V
  - 2.5 V at VDD = 15 V
- 5 V, 10 V and 15 V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices".

#### **Applications:**

- Rate comparators
- General counting applications where display is desired
- Up-down counting applications where input pulses are random in nature

The CD40110B types are supplied in 16-lead dual-in-line ceramic packages (D and F suffixes), and 16-lead dual-in-line plastic package (E suffix), and also available in chip form, (H suffix).

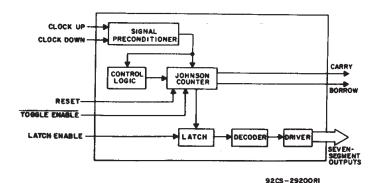


Fig. 1 - Functional diagram.

MAXIMUM RATINGS, Absolute-Maximum Values:	
Voltages referenced to V <sub>SS</sub> Terminal)	0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS	
DC INPUT CURRENT, ANY ONE INPUT	±10mA
For T <sub>A</sub> = -55°C to +100°C	500mW
For T <sub>A</sub> = +100°C to +125°C	Derate Linearity at 12mW/°C to 200mW
For T <sub>A</sub> = -55°C to +100°C  For T <sub>A</sub> = +100°C to +125°C  DEVICE DISSIPATION PER OUTPUT TRANSISTOR  FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	-65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
STORAGE TEMPERATURE RANGE ( $T_{stg}$ )	+265°C

#### **RECOMMENDED OPERATING CONDITIONS**

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

	CHARACTERISTIC	TO SERVICE OF THE SER	V <sub>DD</sub>	LIM MIN.	ITS MAX.	UNITS
Supply-Voltage Range (For TA =	Full Package Temperate	ure Range)	_	3	18	V
Clock Input Frequency (Sum of CLUP & CLDN Freqs.)	fcL	ender tiger gerichten Lieber der Schaufer Gerichte der Schaufer der	5 10 15		1 3 5	MHz
Clock Pulse Width tw			5 10 15	110 40 30	111	
Latch Enable Pulse Width	N	100 (100 (100 (100 (100 (100 (100 (100	5 10 15	110 30 24	1 1 1	· Service
Reset Removal-Time		man Nate of Sant	5 10 15		- -	erre (grade) erre grade) erre grade
Reset Pulse Width			5 10 15	350 170 120	=	

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#### STATIC ELECTRICAL CHARACTERISTICS

		Cond	Itions									1 1 m l h c		
Characteristic			VIN (V)		LIMITS AT INDICATED TEMPERATURES (°C)							Units		
	IOH (mA)	Vон (V)		V <sub>DD</sub> (V)	-55	-40	+85	+125	Min.	+25 Typ.	Max.			
		` '					450	450			_	···		
Quiescent Device				5	5	5	150	150		0.04 0.04	5 10			
Current				10	10	10	300	300		0.04	20	μΑ		
Max. I <sub>DD</sub>	=			15 20	100	20 100	600 3000	600 3000	=	0.04	100			
Output Voltage			0,5	5			.05			0	0.05			
Low-Level			0,10	10			.05			0	∣0.05	V		
Max. V <sub>OŁ</sub>		-	0,15	15		0.	.05			0	0.05			
		<u> </u>	0,5	5	_	_		_	_	4.55				
High-Level Min. VOH	_	_	0,10	10						9.55		V		
Min. VOH	_	_	0,15	15			_			14.55		·		
<u> </u>		I					_							
Input Low Voltage	_	0.5, 3.8		5			.5				1.5	v		
Max. VIL		1, 8.8	_	10			3			=	3	V		
*	-	1.5, 13.8		15	<u> </u>	<del> </del>	4				4			
Innut High Voltage		0.5, 3.8		5	3.8 3.5		_	l —						
Input High Voltage Min. VIH		1, 8.8					7		7			V		
WING VIE	_	1.5, 13.8	<del>-</del>	10 15			1		11					
		]			_	_								
	-	<del></del>		Į I		.9		<u>4</u>	3.9	4.5				
	-5					65		.7	3.7	4.3		4 /		
	-10			5		55		<u>65</u>	3.65	4.25				
	-15		=			.5	3	.5	3.6	4.15		1 '		
	-20 -25	<del>                                     </del>	-		3.45		3.35 3.3		3.45 3,4	3.9		4		
	-23			10		75		.s 85	8.75	9.5				
7-Segment Outputs					10		45		55	8.55	9.3			
Output Drive	-10	<del>                                     </del>						42		.5	8.5	9.25		
Voltage, High	-15	_	_				.4		47	8.47	9.2	<b>-</b>	V	
Min. VOH	-20			†		.4		40	8.45	9.1	<del>  _</del> -	†		
141111. YOH	-25	<del>                                     </del>		1		.3		25	8.3	9	<u> </u>			
				<del> </del>		3.8		3.9	13.8	14.5	_			
	-5	<u> </u>	_	Ī	13	.65		.75	13.75	14.35	_			
	-10		_	15		3.6		.72	13.72	14.3				
	-15		_	] '3	13	3.6	10	3.7	13.7	14.2				
	-20	_	_	]	13	3.6	13	3.6	13.65	14.1				
	-25		·		13	3.3	13	.25	13.3	14.0				
7-Segment Outputs		'		_			A .							
Output Low		0.4	0,5	5	1.28	1.22	0.84	0.72	1	2				
(Sink) Current	<u> </u>	0.5	0, 10	10	3.2	3	2.2	1.8	2.6	5.2		ĺ		
Min. IOL	-	1.5	0, 15	15	8.4	8	5.6	4.8	6.8	13.6	_	}		
Comme October 1	1				<del> </del>					- :	<b>1</b>	Ì		
Carry Outputs Output Low (Sink) Current Min. IOL		0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1				
		0.5	0, 10	10	1.6	1.5	1.1	0.9	1.3	2.6		mA		
	_	1.5	0, 15	15	4.2	4	2.8	2.4	3.4	6.8	_			
Output High	_	4.6	0, 5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1				
(Source) Current		2.5	0, 5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2		1		
Min. IOH		9.5	0, 10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	_	l		
<b>3</b>	_	13.5	0, 15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-			
Input Current Max. I <sub>IN</sub>	-	0, 18	0, 18	18	±0.1	±0.1	±1	±1		±10 <sup>-5</sup>	±0.1	μΑ		

 $<sup>\</sup>blacksquare$  0(10  $\mu$ A)

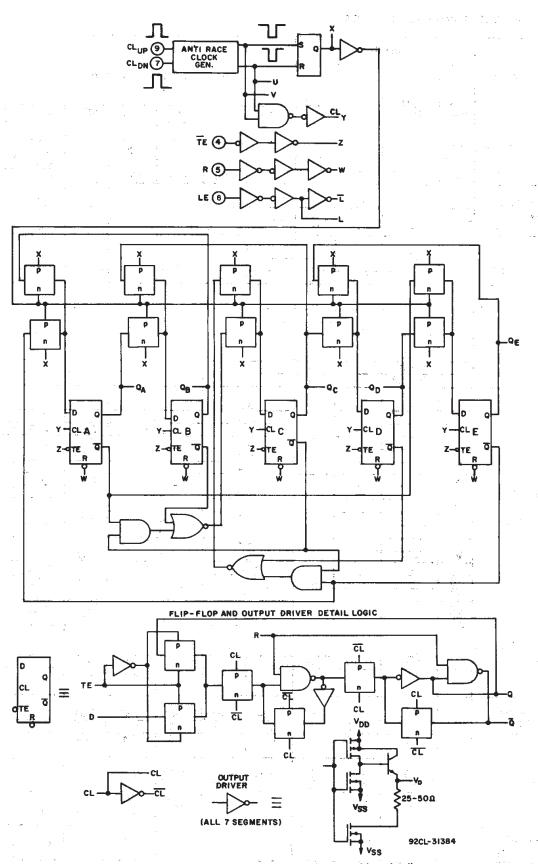


Fig. 2 - Logic diagram with flip-flop and output-driver details. (cont'd on page 5)

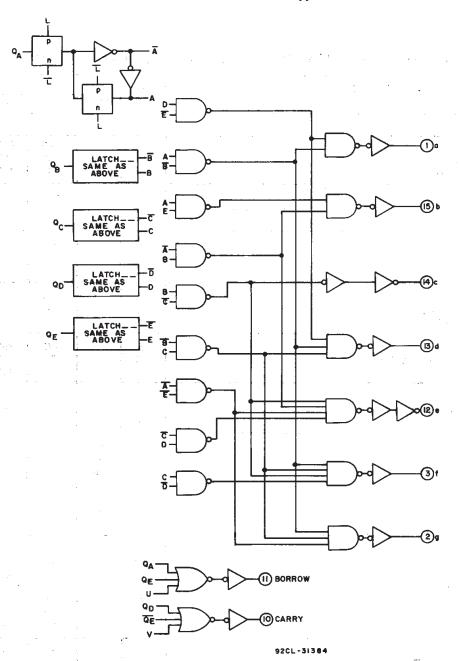
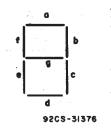
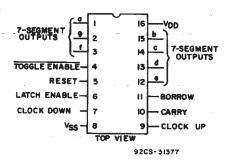


Fig. 2 - Logic diagram with flip-flop and output-driver details.

#### **DISPLAY SEGMENTS**



#### TERMINAL ASSIGNMENT



# DYNAMIC ELECTRICAL CHARACTERISTICS at TA = 25° C, input $t_{\rm f}$ , $t_{\rm f}$ = 20 ns, CL = 50 pF, RL = 200 k $\Omega$

CHARACTERISTI	V <sub>DD</sub>	MIN.	LIMITS TYP.	MAX.	UNITS	
Clock Up/Clock Down						
Propagation Delay Time: Clock to Carry or Borrow	<sup>t</sup> PLH, <sup>t</sup> PHL	5 10 15	<u>-</u> <u>:</u>	300 100 70	600 200 140	
Clock to Segment	tPLH, tPHL	5 10 15	_ 	925 360 250	1850 720 500	ns
Minimum Clock Pulse Width		5 10 15	_ _ _	55 20 15	110 40 30	
Maximum Clock Input Frequency (Sum of CLup & CLDN F)	fcL	5 10 15	1 3 5	2.5 6 8.5	_ _ _	MHz
Minimum Toggle Enable Pulse Width		5 10 15	_ 	175 75 55	350 150 110	
Minimum Latch Enable Pulse Width		5 10 15	_ _ _	55 15 12	110 30 24	
Output Pulse Width: Carry		5 10 15	115 60 40	230 120 75	_	
Borrow		5 10 15	140 65 45	275 130 85		ns
Transition Time: Carry or Borrow	tTLH, tTHL	5 10 15	_ _ _	85 45 30	170 90 60	
Minimum Delay Time Between CLUP & CLDN		5 10 15	_ _	100 80 60	_ _ _	
Maximum Clock Rise or Fall Time	t <sub>r</sub> CL, t <sub>f</sub> CL	5 10 15	<u>-</u> -	<u>-</u>	15 15 15	μs
Reset						
Propagation Delay Time Reset to Output	tPLH, tPHL	5 10 15	-	650 350 160	1300 700 320	
Minimum Reset Removal Time	·	5 10 15	_ _ _	-275 -100 -65	0 0 0	ns
Minimum Reset Pulse Width		5 10 15		175 85 60	350 170 120	

#### TRUTH TABLE

CLOCK UP*	CLOCK DOWN *	LATCH ENABLE	TOGGLE ENABLE	RESET	COUNTER	DISPLAY
	x	0	0	0	Increments by 1	Follows Counter
Х		0	0	0	Decrements by 1	Follows Counter
		×	X	0	No Change	No Change
X	X	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	×	1	Goes to 00000	Remains Fixed
<b>X</b>	×	0	х	<b>1</b> (\$4.75)	Goes to 00000	Follows Counter  (Display = 1/7)
. <b>X</b> .	X	х	1	0	Inhibited	Remains Fixed
	х	1	0	0	Increments by 1	Remains Fixed
. X		<b>1</b>	0	0	Decrements by 1	Remains Fixed

X = Don't Care

<sup>\*</sup> Typically 100 ns between clock-up and clock-down positive transitions are required to ensure proper counting.

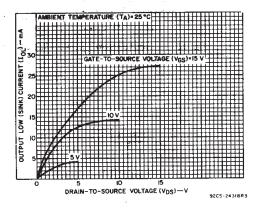


Fig. 3 - Typical carry or borrow output low (sink) current characteristics.

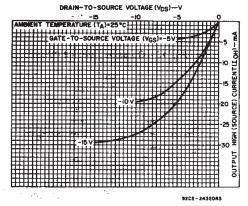


Fig. 5 - Typical carry or borrow output high (source) current characteristics.

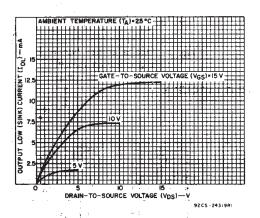


Fig. 4 - Minimum carry or borrow output low (sink) current characteristics.

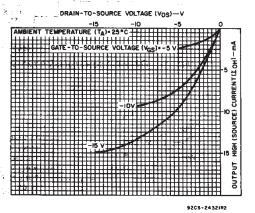


Fig. 6 - Minimum carry or borrow output high (source) current characteristics.

<sup>1 =</sup> High State

<sup>0 =</sup> Low State

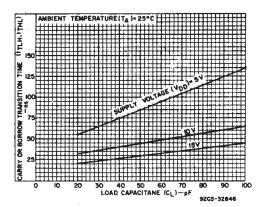


Fig. 7 - Typical carry or borrow transition time vs. load capacitance.

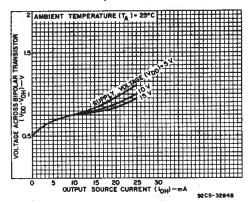


Fig. 9 - Voltage across bipolar transistor vs. output source current.

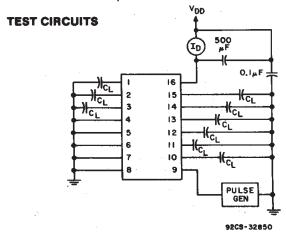


Fig. 11 - Dynamic power dissipation test circuit.

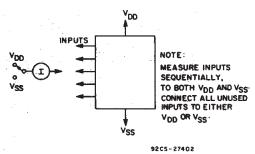


Fig. 13 - Input current.

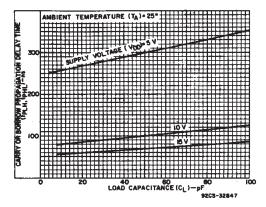


Fig. 8 - Typical carry or borrow propagation delay time vs. load capacitance.

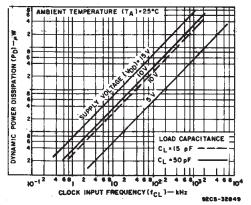


Fig. 10 - Typical dynamic power dissipation vs. frequency.

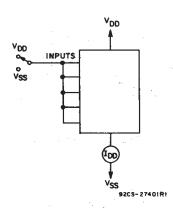


Fig. 12 - Quiescent device current.

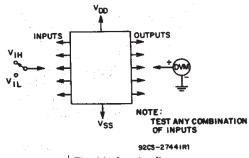


Fig. 14 - Input voltage.

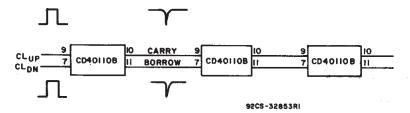
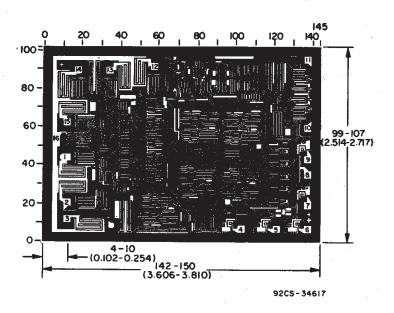


Fig. 15 - Cascading diagram.



Dimensions and pad layout for CD40110B.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10<sup>-3</sup> inch).



#### PACKAGE OPTION ADDENDUM

10-Dec-2020

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
CD40110BE	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD40110BE	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

#### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD40110BE	N	PDIP	16	25	506	13.97	11230	4.32
CD40110BE	N	PDIP	16	25	506	13.97	11230	4.32

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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